

## TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

Assignment ID: TMI190587

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT		
<b>NATURE OF CONVEYANCE:</b>	SECURITY INTEREST		
<b>CONVEYING PARTY DATA</b>			
<b>Name</b>	<b>Formerly</b>	<b>Execution Date</b>	<b>Entity Type</b>
NEVADOS ENGINEERING, INC.		04/24/2024	Corporation: DELAWARE
<b>RECEIVING PARTY DATA</b>			
<b>Company Name:</b>	JPMorgan Chase Bank, N.A.		
<b>Street Address:</b>	383 MADISON AVENUE, 22ND FLOOR		
<b>City:</b>	New York		
<b>State/Country:</b>	NEW YORK		
<b>Postal Code:</b>	10017		
<b>Entity Type:</b>	National Banking Association: UNITED STATES		
<b>PROPERTY NUMBERS Total: 6</b>			
<b>Property Type</b>	<b>Number</b>	<b>Word Mark</b>	
<b>Serial Number:</b>	90739120	NEVADOS	
<b>Serial Number:</b>	90739172	ALL TERRAIN TRACKER	
<b>Serial Number:</b>	90768664	NEVADOS	
<b>Serial Number:</b>	90739100	NEVADOS	
<b>Serial Number:</b>	90739153	ATT	
<b>Serial Number:</b>	90768657	N NEVADOS	
<b>CORRESPONDENCE DATA</b>			
<b>Fax Number:</b>			
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
<b>Phone:</b>	(800)221-0102		
<b>Email:</b>	ipteam@cogencyglobal.com		
<b>Correspondent Name:</b>	Khadijah Sampson		
<b>Address Line 1:</b>	1025 Connecticut Ave NW, Suite 712		
<b>Address Line 2:</b>	COGENCY GLOBAL INC.		
<b>Address Line 4:</b>	Washington, DISTRICT OF COLUMBIA 20036		
<b>ATTORNEY DOCKET NUMBER:</b>	2339705ks		
<b>NAME OF SUBMITTER:</b>	Andrew Hackett		
<b>SIGNATURE:</b>	Andrew Hackett		

OP \$165.00.00 90739120

<b>DATE SIGNED:</b>	04/25/2024
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**Total Attachments: 10**

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## INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Intellectual Property Security Agreement (“Agreement”) is entered into as of April 24, 2024, by and between JPMORGAN CHASE BANK, N.A. (“Lender”), as the lender party to the Credit Agreement referred to below, and NEVADOS ENGINEERING, INC., a Delaware corporation (“Grantor”).

### RECITALS

A. Lender has agreed to make certain advances of money and to extend certain financial accommodation (the “Loans”) to the Loan Parties (as defined in the Credit Agreement), in the amounts and manner set forth in that certain Credit Agreement by and among Lender and the Loan Parties dated as of the same date hereof (as the same may be amended, modified or supplemented from time to time, collectively, the “Credit Agreement”; capitalized terms used herein are used as defined in the Credit Agreement). Lender is willing to make the Loans to the Loan Parties, but only upon the condition, among others, that Grantor shall grant to Lender a security interest in the Collateral, including certain Copyrights, Trademarks, and Patents (as each term is described below) to secure the obligations of Grantor under the Credit Agreement.

B. Pursuant to the terms of the Pledge and Security Agreement, dated as of the date hereof (as the same may be amended, modified or supplemented from time to time, the “Security Agreement”), by and among Lender and the Loan Parties, Grantor has granted to Lender a security interest in all of Grantor’s right, title and interest, whether presently existing or hereafter acquired, in, to and under all of the Collateral.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, as collateral security for the prompt and complete payment when due of its obligations under the Credit Agreement, Grantor hereby represents, warrants, covenants and agrees as follows:

### AGREEMENT

1. Grant of Security Interest. Grantor grants and pledges to Lender a security interest in all of Grantor’s right, title and interest in, to and under its intellectual property (all of which shall collectively be called the “Intellectual Property Collateral”), including, without limitation, the following:

(a) Any and all copyright rights, copyright applications, copyright registrations and like protections in each work of authorship and derivative work thereof, whether published or unpublished and whether or not the same also constitutes a trade secret, now or hereafter existing, created, acquired or held, including without limitation those set forth on Exhibit A attached hereto (collectively, the “Copyrights”);

(b) Any and all trade secrets, and any and all intellectual property rights in computer software and computer software products now or hereafter existing, created, acquired or held;

(c) Any and all design rights that may be available to Grantor now or hereafter existing, created, acquired or held;

(d) All patents, patent applications and like protections including, without limitation, improvements, divisions, continuations, renewals, reissues, extensions and continuations-in-part of the same, including without limitation the patents and patent applications set forth on Exhibit B attached hereto (collectively, the “Patents”);

(e) Any trademark and servicemark rights, whether registered or not, applications to register and registrations of the same and like protections, and the entire goodwill of the business of Grantor connected with and symbolized by such trademarks, including without limitation those set forth on Exhibit C attached hereto (collectively, the "Trademarks");

(g) Any and all claims for damages by way of past, present and future infringements of any of the rights included above, with the right, but not the obligation, to sue for and collect such damages for said use or infringement of the intellectual property rights identified above;

(h) All licenses or other rights to use any of the Copyrights, Patents, or Trademarks, and all license fees and royalties arising from such use to the extent permitted by such license or rights;

(i) All amendments, extensions, renewals and extensions of any of the Copyrights, Trademarks, or Patents; and

(j) All proceeds and products of the foregoing, including without limitation all payments under insurance or any indemnity or warranty payable in respect of any of the foregoing.

2. Recordation. The parties hereto authorize and request that the Commissioner of Patents, the Commissioner for Trademarks and the Register of Copyrights of the United States record this security interest in the Intellectual Property Collateral.

3. Authorization. Grantor hereby authorizes Lender to (a) modify this Agreement unilaterally by amending the exhibits to this Agreement to include any Intellectual Property Collateral which Grantor obtains subsequent to the date of this Agreement, and (b) file a duplicate original of this Agreement containing amended exhibits reflecting such new Intellectual Property Collateral.

4. Loan Documents. This Agreement has been entered into pursuant to and in conjunction with the Security Agreement, which is hereby incorporated by reference. The provisions of the Security Agreement shall supersede and control over any conflicting or inconsistent provision herein. The rights and remedies of Lender with respect to the Intellectual Property Collateral are as provided by the Credit Agreement, Security Agreement and related documents, and nothing in this Agreement shall be deemed to limit such rights and remedies.

5. Execution in Counterparts. This Agreement may be executed in counterparts (and by different parties hereto in different counterparts), each of which shall constitute an original, but all of which when taken together shall constitute a single contract. Delivery of an executed counterpart of a signature page to this Agreement by facsimile or in electronic (i.e., "pdf" or "tif" format) shall be effective as delivery of a manually executed counterpart of this Agreement.

6. Successors and Assigns. This Agreement will be binding on and shall inure to the benefit of the parties hereto and their respective successors and assigns.

7. Governing Law. This Agreement and any claim, controversy, dispute or cause of action (whether in contract or tort or otherwise) based upon, arising out of or relating to this Agreement and the transactions contemplated hereby and thereby shall be governed by, and construed in accordance with, the laws of the United States and the State of New York, without giving effect to any choice or conflict of law provision or rule (whether of the State of New York or any other jurisdiction).

[Signatures included on the following page]

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

GRANTOR:

Address:

55 4<sup>th</sup> Street  
Oakland, CA 94607  
Attention: Richard Baldini

NEVADOS ENGINEERING, INC.

By: 

Name: Yezin Taha

Title: Chief Executive Officer

LENDER:

Address:

383 Madison Avenue, 22<sup>nd</sup> Floor  
New York, NY 10017  
Attention: Jared Friedberg

JPMORGAN CHASE BANK, N.A.

By: \_\_\_\_\_

Name: Jared Friedberg

Title: Authorized Officer

*[Signature page to Intellectual Property Security Agreement]*

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

GRANTOR:

Address:

**NEVADOS ENGINEERING, INC.**

55 4<sup>th</sup> Street  
Oakland, CA 94607  
Attention: Richard Baldini

By: \_\_\_\_\_

Name: Yezin Taha

Title: Chief Executive Officer

LENDER:

Address:

**JPMORGAN CHASE BANK, N.A.**

383 Madison Avenue, 22<sup>nd</sup> Floor  
New York, NY 10017  
Attention: Jared Friedberg

By: Jared Friedberg

Name: Jared Friedberg

Title: Authorized Officer

*[Signature page to Intellectual Property Security Agreement]*

**TRADEMARK  
REEL: 008410 FRAME: 0057**

EXHIBIT A

Copyrights

None.

EXHIBIT B

Patents

See attached.









<b>Document/Patent number</b>	<b>Title</b>	<b>Owner</b>	<b>Publication date</b>
US-11929705-B2	Articulating joint solar panel array	Nevados Engineering, Inc.	3/12/2024
US-20230402960-A1	METHODS AND DEVICES FOR ADAPTING A SOLAR MODULE SUPPORT	Nevados Engineering, Inc.	12/14/2023
US-20230396210-A1	PONY MODULE FOR SOLAR TRACKER	Nevados Engineering, Inc.	12/7/2023
US-20230327603-A1	SECURING DEVICE FOR SOLAR PANEL	Nevados Engineering, Inc.	10/12/2023
US-11757402-B2	Integrated articulated bearing	Nevados Engineering, Inc.	9/12/2023
US-11728761-B2	Articulating joint solar panel array	Nevados Engineering, Inc.	8/15/2023
US-11716051-B2	Flexure bearing assembly	Nevados Engineering, Inc.	8/1/2023
US-20230223890-A1	ARTICULATING JOINT SOLAR PANEL ARRAY	Nevados Engineering, Inc.	7/13/2023
US-20230208349-A1	VARIABLE TERRAIN SOLAR TRACKER	Nevados Engineering, Inc.	6/29/2023
US-20230132976-A1	ARTICULATING JOINT SOLAR PANEL ARRAY	Nevados Engineering, Inc.	5/4/2023
US-20230133584-A1	ARTICULATING JOINT SOLAR PANEL ARRAY	Nevados Engineering, Inc.	5/4/2023
US-11626832-B2	Module clip	Nevados Engineering, Inc.	4/11/2023
US-11581845-B2	Integrated bearing assembly	Nevados Engineering, Inc.	2/14/2023
US-11558008-B2	Row-end cantilevered beam module support	Nevados Engineering, Inc.	1/17/2023
US-11539325-B2	Variable terrain solar tracker	Nevados Engineering, Inc.	12/27/2022
US-11515832-B2	Thrust surface bearing	Nevados Engineering, Inc.	11/29/2022
US-20220186775-A1	THRUST SURFACE BEARING	Nevados Engineering, Inc.	6/16/2022
US-20220186982-A1	MODULE CLIP	Nevados Engineering, Inc.	6/16/2022

US-20220187409-A1	MECHANICAL STOP ASSEMBLY	Nevados Engineering, Inc.	6/16/2022
US-20220190677-A1	OUTBOARD FLEXURE BEARING ASSEMBLY	Nevados Engineering, Inc.	6/16/2022
US-20220190774-A1	INTEGRATED BEARING ASSEMBLY	Nevados Engineering, Inc.	6/16/2022
US-20220190775-A1	ROW-END CANTILEVERED BEAM MODULE SUPPORT	Nevados Engineering, Inc.	6/16/2022
US-20220190776-A1	INTEGRATED ARTICULATED BEARING	Nevados Engineering, Inc.	6/16/2022
US-20220190777-A1	FLEXURE BEARING ASSEMBLY	Nevados Engineering, Inc.	6/16/2022
US-20220166373-A1	ARTICULATING JOINT SOLAR PANEL ARRAY	Nevados Engineering, Inc.	5/26/2022
US-11251745-B2	Articulating joint solar panel array	Nevados Engineering, Inc.	2/15/2022
US-20200052644-A1	VARIABLE TERRAIN SOLAR TRACKER	Nevados Engineering, Inc.	2/13/2020
US-20170366133-A1	ARTICULATING JOINT SOLAR PANEL ARRAY	Nevados Engineering, Inc.	12/21/2017

EXHIBIT C

Trademarks

See Attached.

SerialNumber	Wordmark	Image	Status	GoodsAndServicesTruncated	Basiss	FiledDate	InternationalClass	OwnerFullText	PriorityDate	RegistrationDate	RegistrationNumber	RegistrationType	SupplementalRegistrationDate
90729120	NEVADOS		Live	IC 007: Mechanical systems for operation of solar power plants, namely, solar trackers, foundations, bearings, controllers, and torque tubes.	1a	2021-05-27T00:00:00	IC 007	Nevados Engineering, Inc. (CORPORATION); DELAWARE, USA); Suite 408, 350 Townsend Street, San Francisco, CALIFORNIA 94107, UNITED STATES		2022-06-07	6751874	PRINCIPAL	
90729172	ALL TERRAIN TRACKER		Live	IC 007: Mechanical systems for operation of solar power plants, namely, solar trackers, foundations, bearings, controllers, and torque tubes.	1a	2021-05-27T00:00:00	IC 007	Nevados Engineering, Inc. (CORPORATION); DELAWARE, USA); Suite 408, 350 Townsend Street, San Francisco, CALIFORNIA 94107, UNITED STATES		2022-03-29	6688450	SUPPLEMENTAL	2022-02-11
90726864	NEVADOS		Live	IC 009: Downloadable and recorded software for operation of solar power plants.	1b	2021-06-11T00:00:00	IC 009	Nevados Engineering, Inc. (CORPORATION); DELAWARE, USA); Suite 408, 350 Townsend Street, San Francisco, CALIFORNIA 94107, UNITED STATES				PRINCIPAL	
90729102	NEVADOS		Live	IC 007: Mechanical systems for operation of solar power plants, namely, solar trackers, foundations, bearings, controllers, and torque tubes.	1a	2021-05-27T00:00:00	IC 007	Nevados Engineering, Inc. (CORPORATION); DELAWARE, USA); Suite 408, 350 Townsend Street, San Francisco, CALIFORNIA 94107, UNITED STATES		2022-06-07	6751873	PRINCIPAL	
90729153	ATT		Live	IC 007: Mechanical systems for operation of solar power plants, namely, solar trackers, foundations, bearings, controllers, and torque tubes.	1a	2021-05-27T00:00:00	IC 007	Nevados Engineering, Inc. (CORPORATION); DELAWARE, USA); Suite 408, 350 Townsend Street, San Francisco, CALIFORNIA 94107, UNITED STATES		2022-06-07	6751878	PRINCIPAL	
90726867	N NEVADOS		Live	IC 009: Downloadable and recorded software for operation of solar power plants.	1b	2021-06-11T00:00:00	IC 009	Nevados Engineering, Inc. (CORPORATION); DELAWARE, USA); Suite 408, 350 Townsend Street, San Francisco, CALIFORNIA 94107, UNITED STATES				PRINCIPAL	

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REEL: 008410 FRAME: 0063

RECORDED: 04/25/2024